562/564 Series

Circuit Board Mount Blocks for TE5/TR5 Type Fuses

RoHS





564 Series Holder

Additional Information



Resources 562 Series



Resources 564 Series



Accessories 564 Series



Samples 562 Series



Samples 564 Series



| | 562 Series | 564 Series | |
|-------------------------|--|--------------------|--|
| Compatible Fuses | TR5/TE5 | | |
| Materials | Block: Black Thermoplastic, UL94 V-0 PET | | |
| | Terminals: Copper alloy; solderable tinned | | |
| Electrical Data (0000) | Rated Voltage: 250V | | |
| Electrical Data (23°C) | Max. Current/Power: 6.3A/1.6W | | |
| Mounting | PC Board, | PC Board, | |
| | 5.08mm pin spacing | 5.08mm pad spacing | |
| Minimum Cross | Conducting path - | Conducting path - | |
| Section | 0.1mm ² | 0.1mm ² | |
| Unit Weight | 0.12g | 0.44g | |
| Ambient Temperature | - 40°C to + 85°C | | |

Ordering Information

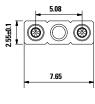
| Ordering Number | Circuit Board Mounting | Packaging |
|-----------------|------------------------|-------------------|
| 56200001009 | Thru-Hole | 1000 (Bulk pack) |
| 56400001009 | Surface Mount | 1500 (Tape /Reel) |

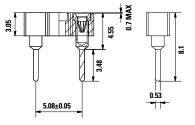
Agency Approvals

| Agency | Agency File Number | |
|-----------|--------------------|------------|
| | 562 Series | 564 Series |
| 71 | E14721 | E14721 |

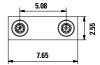
Dimensions units in mm

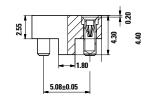
562 Series Holder



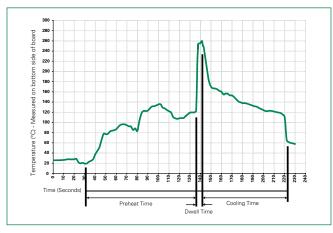


564 Series Holder





Soldering Parameters - Wave Soldering



Soldering Parameters - Reflow Soldering

| Reflow Condition | | Pb - Free assembly |
|--|---|------------------------|
| Number of allowed reflow cycles | | 3 |
| Pre Heat | -Temperature Min (T _{s(min)}) | 150°C |
| | -Temperature Max (T _{s(max)}) | 200°C |
| | -Time (Min to Max) (t _s) | 60 - 120 Secs. |
| Average ramp up rate (Liquidus Temp (T_L) to peak | | 5°C/second max. |
| T _{s(max)} to T _L - Ramp-up Rate | | 5°C/second max. |
| Reflow | - Temperature (T_L) (Liquidus) | 217°C |
| | -Temperature (t _L) | 60 - 150 seconds |
| Peak Temperature (T _P) | | 240 ^{+/-5} °C |
| Time within 5oC of actual peak Temperature ($t_{\rm p}$) | | 30 secs. max. |
| Ramp-down Rate | | 5°C/second max. |
| Time 25°C to peak Temperature (T _P) | | 8 minutes max. |
| Do not exceed | | 245°C |

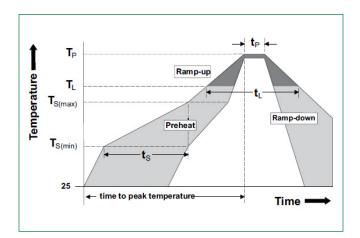
Recommended Process Parameters:

| Wave Parameter | Lead-Free Recommendation | |
|--|-----------------------------------|--|
| Preheat: (Depends on Flux Activation Temperature) | (Typical Industry Recommendation) | |
| Temperature Minimum: | 100°C | |
| Temperature Maximum: | 150°C | |
| Preheat Time: | 60-180 seconds | |
| Solder Pot Temperature: | 260°C Maximum | |
| Solder Dwell Time: | 2-5 seconds | |

Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350°C +/- 5°C

Heating time: 5 seconds max **Note:** These devicess are not recommended for IR and Convection Reflow process



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